

RoHS

COMPLIANT

HALOGEN

FREE

P-Channel 20-V (D-S) MOSFET

MOSFET PRODUCT SUMMARY						
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)			
	0.035 at V _{GS} = - 10 V	- 5 ^e				
- 20	0.043 at V _{GS} = - 4.5 V	- 5 ^e	10 nC			
	0.061 at V _{GS} = - 2.5 V	- 4.8				

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested ٠
- Compliant to RoHS Directive 2002/95/EC ٠

APPLICATIONS

- · Load Switch
- PA Switch
- DC/DC Converters •

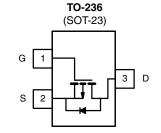
ABSOLUTE MAXIMUM RATINGS ($T_A =$	25 °C, unless ot	herwise noted)		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 20	V	
Gate-Source Voltage	V _{GS}	± 12	v	
	T _C = 25 °C		- 5 ^e	
Continuous Drain Current (T ₁ = 150 °C)	T _C = 70 °C	I _D	- 4.8	
	T _A = 25 °C	טי	- 4.5 ^{b, c}	
	T _A = 70 °C		- 3.5 ^{b, c}	А
Pulsed Drain Current	I _{DM}	- 18	7	
Continuous Source-Drain Diode Current $T_{C} = 25 \text{ °C}$		۱ _S	- 2.1	
Continuous Source-Drain Diode Current	T _A = 25 °C	'S	- 1.0 ^{b, c}	
	T _C = 25 °C		2.5	
Maximum Power Dissipation	T _C = 70 °C	PD	1.6	w
Maximum Fower Dissipation	T _A = 25 °C	۰D	1.25 ^{b, c}	~~~~
	T _A = 70 °C		0.8 ^{b, c}	7
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	≤5 s	R _{thJA}	75	100	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	40	50	0/11

Notes:

- a. Based on T_C = 25 °C. b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 166 °C/W.

e. Package limited.



PMV48XP

$\begin{array}{ c c c c c } \hline Parameter & Symbol & Test Conditions & Min. Typ. Max. Unit \\ \hline Static \\ \hline Drain-Source Breakdown Voltage & V_{DS} & V_{DS} = 0 V, I_{D} = \cdot 250 \mu A & -20 & & V \\ \hline V_{DS} Temperature Coefficient & AV_{DS}(T_J & I_{D} = \cdot 250 \mu A & -20 & & -13.4 & V \\ \hline V_{DS} Temperature Coefficient & AV_{OS}(m) & V_{DS} = V_{DS}, I_{D} = \cdot 250 \mu A & -0.5 & & -1.5 & V \\ \hline Cate-Source Leakage & V_{DS} & V_{DS} = 0 V, V_{OS} = 12 V & & -10 & \mu A \\ \hline Cate-Source Leakage & V_{DS} & V_{DS} = 0 V, V_{OS} = 0 V, V_{OS} = 0 V & -1 & +10 & 0 & \Lambda \\ \hline V_{DS} = -20 V, V_{OS} = 0 V, V_{DS} = 0 V & -18 & & -10 & 0 & \Lambda \\ \hline V_{DS} = -20 V, V_{OS} = 0 V, I_{D} = -51 \Lambda & & 0.003 & & -10 & 0 \\ \hline On-State Drain Current^a & I_{D}(m) & V_{DS} = -5 V, V_{DS} = -4.5 V & -18 & & 0.003 & & 0 \\ \hline On-State Drain Current^a & I_{D}(m) & V_{DS} = -5 V, I_{D} = -5.1 \Lambda & & 0.004 & & 0.004 & & 0 \\ \hline Orward Tansconductance^a & g_{IS} & V_{DS} = -10 V, V_{OS} = 0 V, I_{D} = -5.1 \Lambda & & 0.0061 & & & 0 \\ \hline Supanic^b & & & & & & & & & & & & & & & & & & &$	MOSFET SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Static							
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 V, I_{D} = -250 \mu A$	- 20			V	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $			L _ 250 uA		- 13.4		m\//ºC	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	V _{GS(th)} Temperature Coefficient		5		2.9		1110/ 0	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate-Source Threshold Voltage	V _{GS(th)}		- 0.5		- 1.5	V	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate-Source Leakage	I _{GSS}				± 100	nA	
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	Zara Gata Valtaga Drain Current		$V_{DS} = -20 V, V_{GS} = 0 V$					
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Zero Gale voltage Drain Current	USS	V_{DS} = - 20 V, V_{GS} = 0 V, T_{J} = 55 °C			- 10	μΑ	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	On-State Drain Current ^a	I _{D(on)}	V_{DS} \leq - 5 V, V_{GS} = - 4.5 V	- 18			А	
$ \begin{array}{ c c c c c c } \hline V_{GS} = - 2.5 \ V, \ I_D = - 3.7 \ A & 0.061 & \\ \hline V_{GS} = - 2.5 \ V, \ I_D = - 5.1 \ A & 15 & \\ \hline S & \\ \hline \\$			V _{GS} = - 10 V, I _D = - 5.1 A		0.035			
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 4.5 A		0.043		Ω	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $			V _{GS} = - 2.5 V, I _D = - 3.7 A		0.061			
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Forward Transconductance ^a	9 _{fs}	V _{DS} = - 5 V, I _D = - 5.1 A		15		S	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Dynamic ^b	•			•	•		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Input Capacitance	C _{iss}			835		pF	
$ \begin{array}{c c c c c c c } \hline Reverse Transfer Capacitance & C_{rss} & 155 & 16 \\ \hline Total Gate Charge & Q_g & $V_{DS} = -10 \ V, V_{GS} = -4.5 \ V, I_D = -5.1 \ A & 10 & 165 & 16 \\ \hline Gate-Source Charge & Q_{gd} & $V_{DS} = -10 \ V, V_{GS} = -2.5 \ V, I_D = -5.1 \ A & 1.7 & $$	Output Capacitance	C _{oss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		180			
$ \begin{array}{ c c c c c } \hline \mbox{Idial Gate Charge} & Q_g & Q_{gs} & V_{DS} = -10 \ V, \ V_{GS} = -2.5 \ V, \ I_D = -5.1 \ A & 1.7 & 0.9 & $	Reverse Transfer Capacitance				155			
$ \begin{array}{ c c c c } \hline \begin{tabular}{ c c c c } \hline \end{tabular} \\ \hline \end{tabular} \hline ta$	Tatal Cata Charge	0	V_{DS} = - 10 V, V_{GS} = - 4.5 V, I_D = - 5.1 A		10		nC	
$ \begin{array}{c c c c c c c } \hline Gate-Source Charge & Q_{gs} & V_{DS} = -10 \ V, \ V_{GS} = -2.5 \ V, \ I_D = -5.1 \ A & 1.7 & 1.7 & 3.4$	Total Gate Charge	Qg	V _{DS} = - 10 V, V _{GS} = - 2.5 V, I _D = - 5.1 A		6.4			
$ \begin{array}{c c c c c c c c } \hline Gate-Drain Charge & Q_{gd} & & & & & & & & & & & & & & & & & & &$	Gate-Source Charge	Q _{gs}			1.7			
$\begin{tabular}{ c c c c c c c c c c } \hline Turn-On Delay Time & t_d(on) & t_r & V_{DD} = -10 \ V, \ R_L = 2.4 \ \Omega & 20 & 30 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 &$	Gate-Drain Charge				3.4			
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate Resistance	R _g	f = 1 MHz	0.9	4.4	8.8	Ω	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Turn-On Delay Time	t _{d(on)}			22	33		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Rise Time		V_{DD} = - 10 V, R_L = 2.4 Ω		20	30	ns	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Turn-Off Delay Time	t _{d(off)}	I_D = - 4.1 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		28	42		
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Fall Time				9	18		
Pulse Diode Forward Current ^a Ism-20ABody Diode Voltage V_{SD} $I_S = -4.1 \text{ A}$ -0.8 -1.2 VBody Diode Reverse Recovery Time t_{rr} 2335nsBody Diode Reverse Recovery Charge Q_{rr} $I_F = -4.1 \text{ A}$, dl/dt = 100 A/µs, $T_J = 25 \text{ °C}$ 1220nCReverse Recovery Fall Time t_a ns ns ns	Drain-Source Body Diode Characteristi	cs						
Pulse Diode Forward Current ^a Ism- 20Body Diode Voltage V_{SD} $I_S = -4.1 \text{ A}$ - 0.8- 1.2VBody Diode Reverse Recovery Time t_{rr} 2335nsBody Diode Reverse Recovery Charge Q_{rr} $I_F = -4.1 \text{ A}$, $dI/dt = 100 \text{ A/}\mu \text{s}$, $T_J = 25 \text{ °C}$ 1220nCReverse Recovery Fall Time t_a nsnsns	Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 2.1		
Body Diode Reverse Recovery Time t_{rr} 2335nsBody Diode Reverse Recovery Charge Q_{rr} Reverse Recovery Fall Time t_a	Pulse Diode Forward Current ^a	I _{SM}				- 20	A	
Body Diode Reverse Recovery Charge Q_{rr} $I_F = -4.1 \text{ A}, dI/dt = 100 \text{ A}/\mu \text{s}, T_J = 25 \text{ °C}$ 1220nCReverse Recovery Fall Time t_a 15ns	Body Diode Voltage	V _{SD}	I _S = - 4.1 A		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Charge Q_{rr} $I_F = -4.1 \text{ A}, dI/dt = 100 \text{ A}/\mu \text{s}, T_J = 25 \text{ °C}$ 1220nCReverse Recovery Fall Time t_a 15ns	Body Diode Reverse Recovery Time	t _{rr}			23	35	ns	
Reverse Recovery Fall Time t_a $I_F = -4.1 \text{ A}$, $dl/dt = 100 \text{ A}/\mu \text{s}$, $I_J = 25 \text{ °C}$ 15	Body Diode Reverse Recovery Charge				12	20	nC	
ns ns	Reverse Recovery Fall Time	1	$I_F = -4.1 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, I_J = 25 \text{ °C}$		15			
					8		– ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

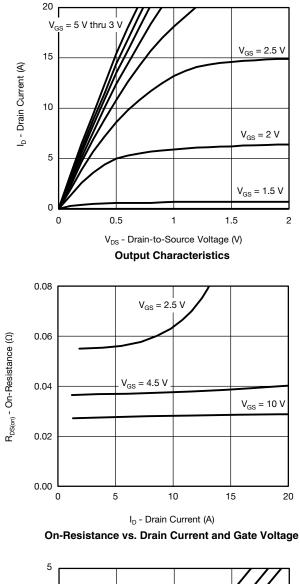
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

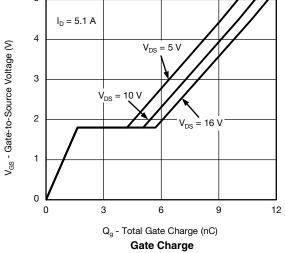
Bsemi

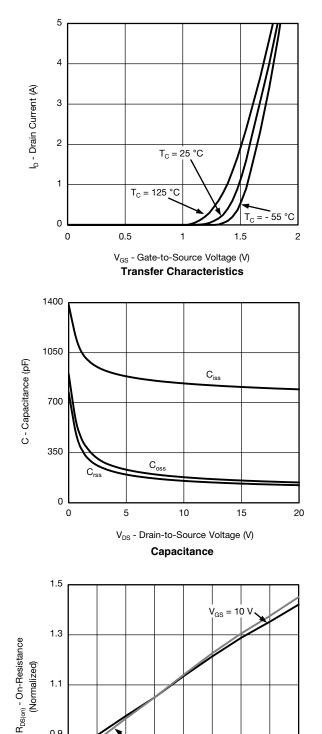
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)







0.9

0.7

- 50

- 25

 $V_{GS} = 4.5 V$

0

25

50

T_J - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

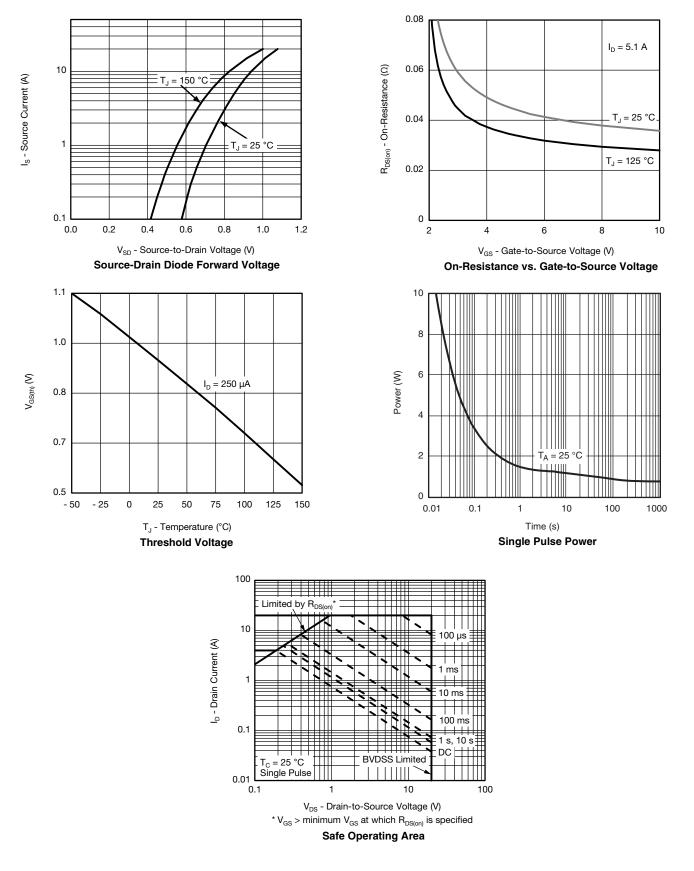
75

100

125 150

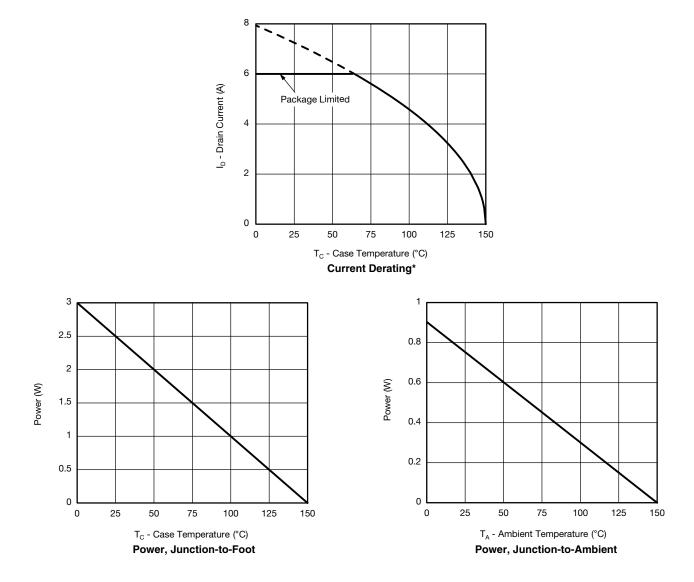


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





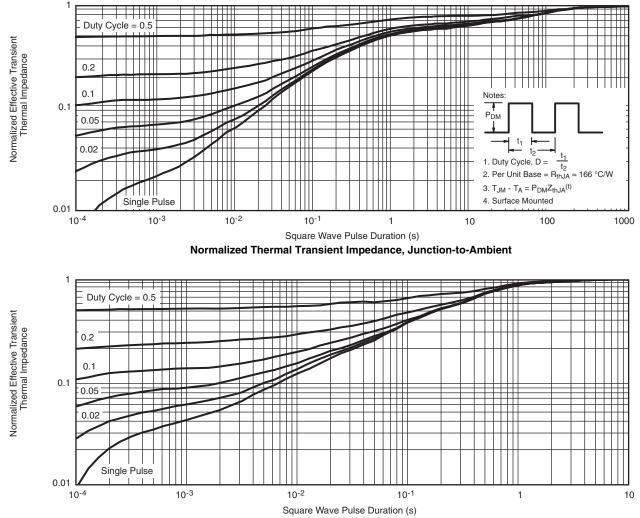
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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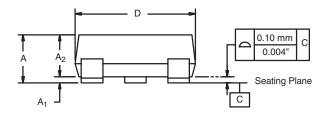


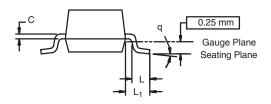
Normalized Thermal Transient Impedance, Junction-to-Foot



SOT-23 (TO-236): 3-LEAD







Dim	MILLIN	METERS	INCHES		
	Min	Мах	Min	Мах	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
C	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95	BSC	0.0374 Ref		
e ₁	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025	Ref	
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
ECN: S-03946-Rev. K, 09- DWG: 5479	Jul-01	•	·		



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)

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